



June 2016

FFSH15120ADN_F155

Silicon Carbide Schottky Diode

1200 V, 15 A

Features

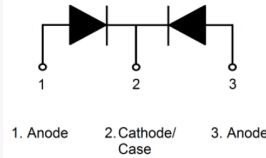
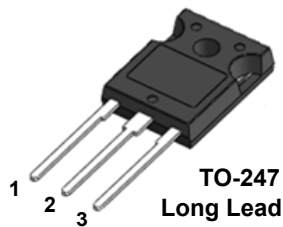
- Max Junction Temperature 175 °C
- Avalanche Rated 80 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

Description

SiC Schottky Diode has no switching loss, provides improved system efficiency against Si diodes by utilizing new semiconductor material - Silicon Carbide, enables higher operating frequency, and helps increasing power density and reduction of system size/cost. Its high reliability ensures robust operation during surge or over-voltage conditions



Absolute Maximum Ratings $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted. (per leg)

Symbol	Parameter	FFSH15120ADN_F155	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	1200	V
E_{AS}	Single Pulse Avalanche Energy (Note 1)	80	mJ
I_F	Continuous Rectified Forward Current @ $T_C < 148\text{ }^\circ\text{C}$	8* / 15**	A
$I_{F, Max}$	Non-Repetitive Peak Forward Surge Current	$T_C = 25\text{ }^\circ\text{C}$, 10 μs	560
		$T_C = 150\text{ }^\circ\text{C}$, 10 μs	500
$I_{F, SM}$	Non-Repetitive Forward Surge Current	Half-Sine Pulse, $t_p = 8.3\text{ ms}$	80
$I_{F, RM}$	Repetitive Forward Surge Current	Half-Sine Pulse, $t_p = 8.3\text{ ms}$	36
P_{tot}	Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	110
		$T_C = 150\text{ }^\circ\text{C}$	19
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
	TO247 Mounting Torque, M3 Screw	60	Ncm

Thermal Characteristic

Symbol	Parameter	FFSH15120ADN_F155	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	1.35* / 0.56**	$^\circ\text{C/W}$

* Per leg, ** Per Device

FFSH15120ADN_F155 — Silicon Carbide Schottky Diode

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFSH15120ADN_F155	FFSH15120ADN	TO-247 Long Lead	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted. (per leg)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Forward Voltage	$I_F = 8\text{ A}, T_C = 25^\circ\text{C}$	-	1.45	1.75	V
		$I_F = 8\text{ A}, T_C = 125^\circ\text{C}$	-	1.7	2	
		$I_F = 8\text{ A}, T_C = 175^\circ\text{C}$	-	2	2.4	
I_R	Reverse Current	$V_R = 1200\text{ V}, T_C = 25^\circ\text{C}$	-	-	200	μA
		$V_R = 1200\text{ V}, T_C = 125^\circ\text{C}$	-	-	300	
		$V_R = 1200\text{ V}, T_C = 175^\circ\text{C}$	-	-	400	
Q_C	Total Capacitive Charge	$V = 800\text{ V}$	-	55	-	nC
C	Total Capacitance	$V_R = 1\text{ V}, f = 100\text{ kHz}$	-	538	-	pF
		$V_R = 400\text{ V}, f = 100\text{ kHz}$	-	50	-	
		$V_R = 800\text{ V}, f = 100\text{ kHz}$	-	40	-	

Notes:

1: EAS of 80 mJ is based on starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{ mH}$, $I_{AS} = 18\text{ A}$, $V = 150\text{ V}$.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted (per leg).

Figure 1. Forward Characteristics

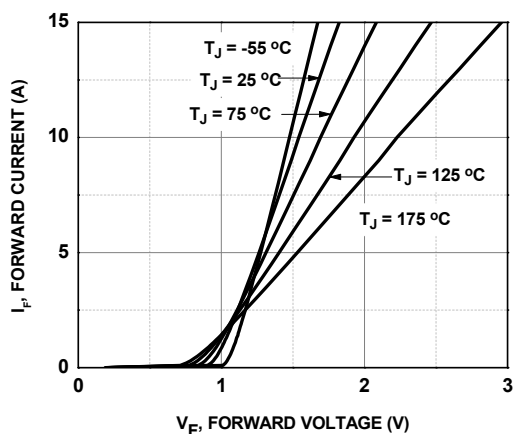


Figure 2. Reverse Characteristics

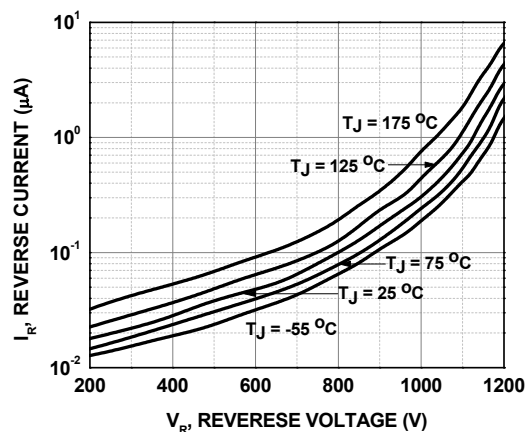


Figure 3. Reverse Characteristics

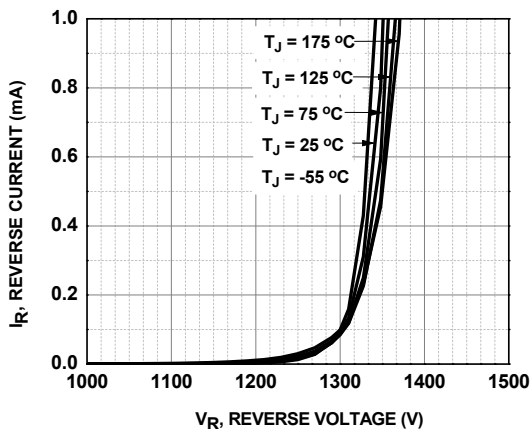
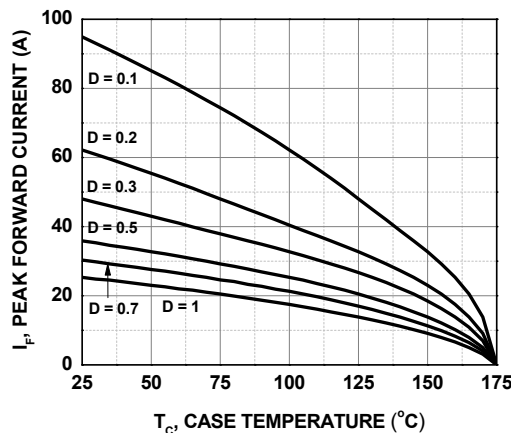


Figure 4. Current Derating



Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted (per leg, continue).

Figure 5. Power Derating

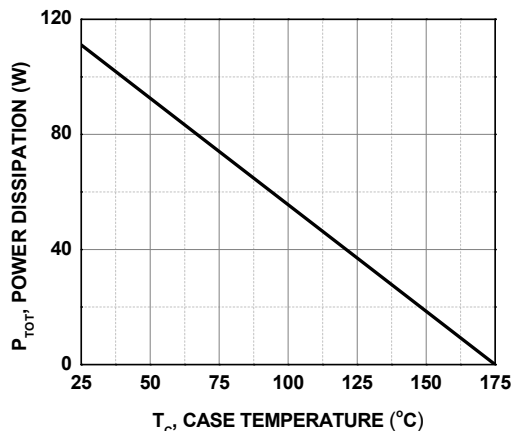


Figure 6. Capacitive Charge vs. Reverse Voltage

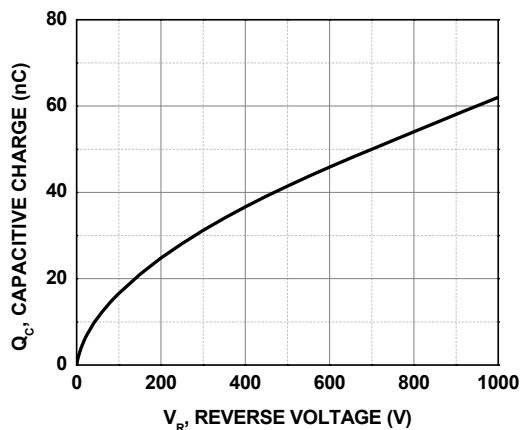


Figure 7. Capacitance vs. Reverse Voltage

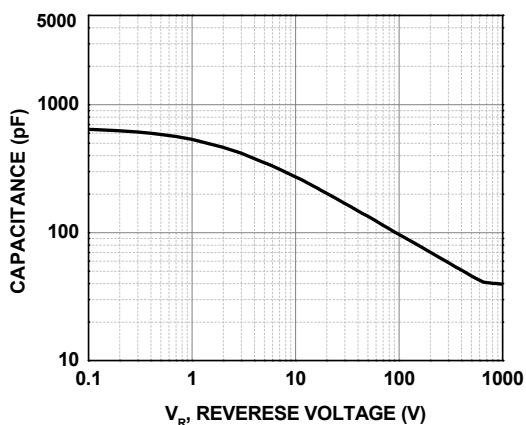


Figure 8. Capacitance Stored Energy

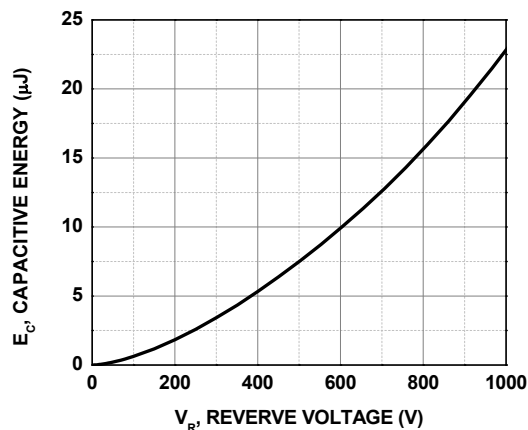
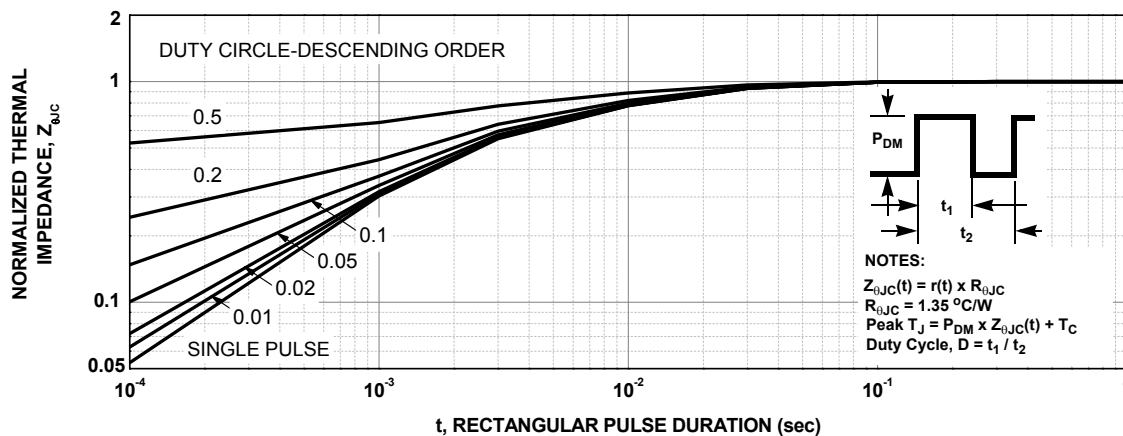


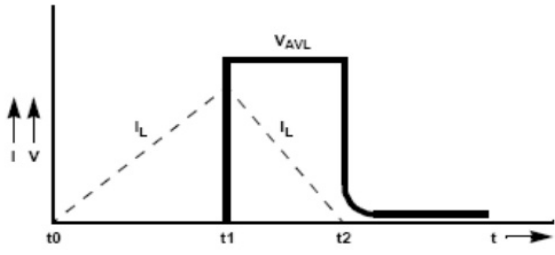
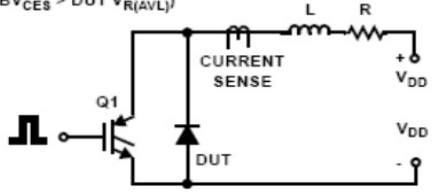
Figure 9. Junction-to-Case Transient Thermal Response Curve

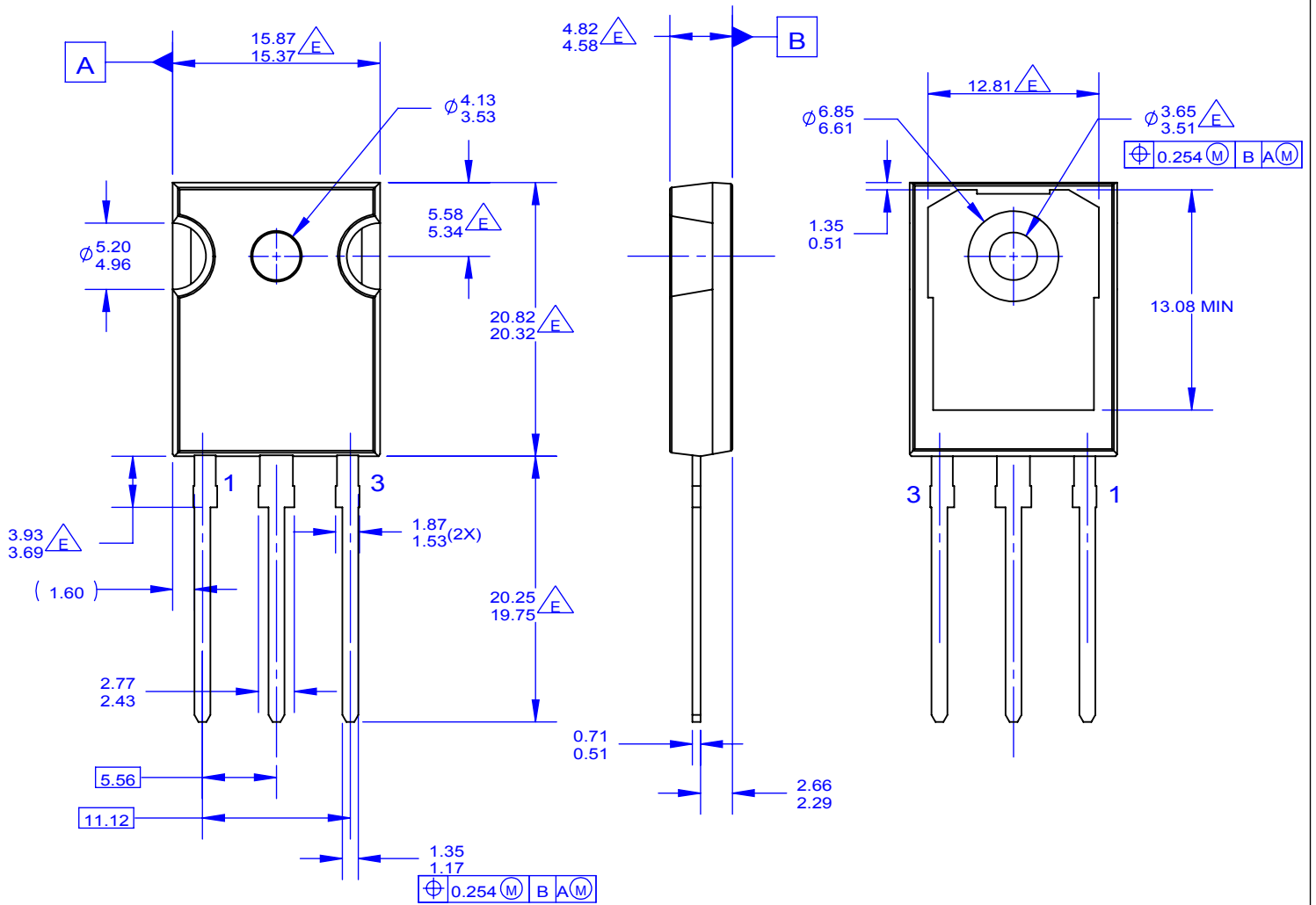


Test Circuit and Waveforms

Figure 10. Unclamped Inductive Switching Test Circuit & Waveform

L = 0.5mH
 R < 0.1Ω
 V_{DD} = 50V
 $E_{AVL} = 1/2 L I^2 [V_{R(AVL)} / (V_{R(AVL)} - V_{DD})]$
 Q1 = IGBT (BV_{CES} > DUT V_{R(AVL)})





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